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(74) **Agent: ZITZMANN, Oliver, A., M.;** Advanced Technology Materials, Inc., 7 Commerce Drive, Danbury, CT 06810 (US).

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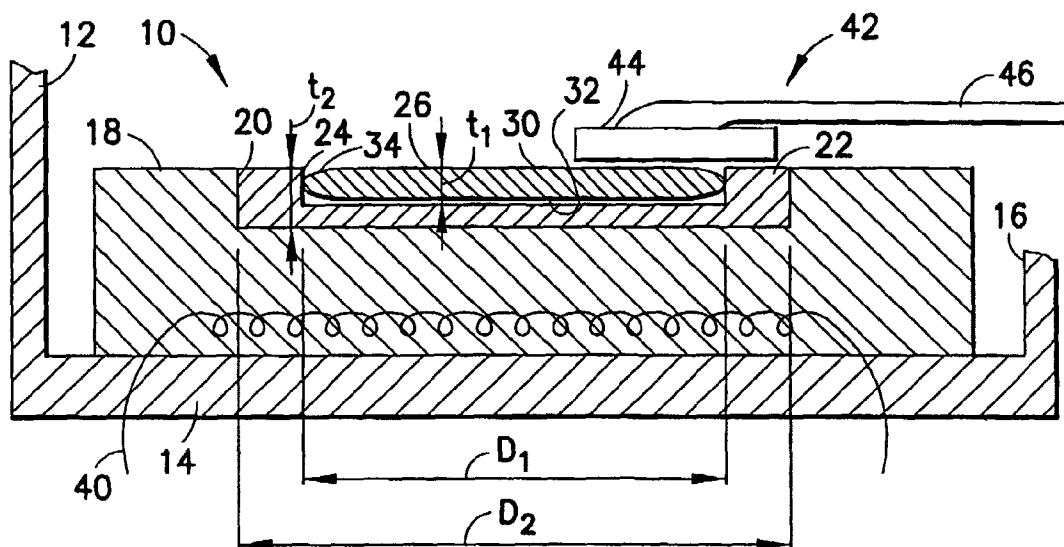
(71) Applicant: ADVANCED TECHNOLOGY MATERIALS, INC. [US/US]; 7 Commerce Drive, Danbury, CT 06810 (US).

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(72) Inventor: TISCHLER, Michael, A.; 1401 West Saltsage Drive, Phoenix, AZ 85045 (US).

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(54) Title: WATER CARRIER FOR SEMICONDUCTOR PROCESS TOOL



(57) Abstract: A wafer carrier enabling a wafer of different size and/or shape to be processed in a process tool configured for processing a wafer of a predetermined size and/or shape, wherein the wafer carrier has such predetermined size and/or shape and includes at least one recess therein having the different size and/or shape. The wafer carrier enables the use in a process tool (e.g., a semiconductor epitaxial thin film deposition reactor such as a single wafer reactor) of differently sized wafers than those for which the process tool is designed.



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